

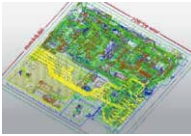
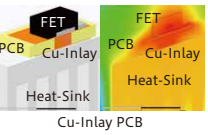
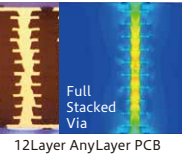




# 計測技術受託サービス




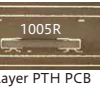


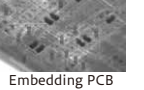

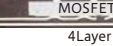
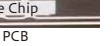


## Electronics Assembly and Interconnect Engineering Service

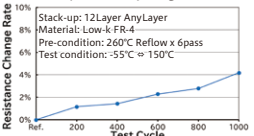
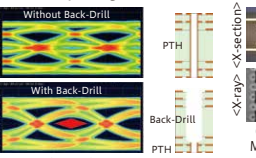
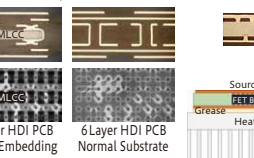
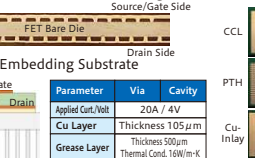

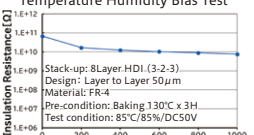

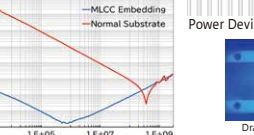
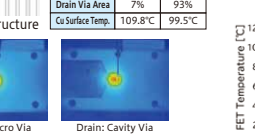
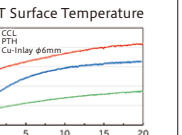
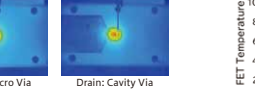
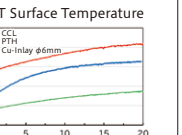
### 特長 Features

- プリント配線板の設計・製造・実装で培った技術でお客様の原理検証・先行開発をサポートします  
To Support Customer's POC Development with Meiko's Technology Experienced in PCB's design, manufacturing and Assembly
- 100GHz帯までの材料誘電特性と伝送線路の計測、電磁界解析、熱解析、応力解析、測定基板製造を提供します  
Measurement of Material Dk/Df & PCB S-Parameter, Simulation of SI/PI & Electronics Cooling & Thermal Stress, DUT/PCB Manufacturing

お客様 Customer	御依頼内容実績 Offering Services	設計 解析 Design Simulation	基板 製造 PCB Manufacturing	部品 実装 Device Ass'y	誘電 特性 Dk/Df Measure	伝送 特性 S-Para Measure	加工 条件 Process Condition	基板 分析 PCB Analysis	信頼性 試験 Reliability Test	特性 評価 Performance Evaluation
材料メーカー Material Supplier	比誘電率/誘電正接 測定 Dk/Df Measurement				✓					
	材料開発支援 Material Development Support	✓	✓		✓	✓	✓	✓	✓	
基板メーカー Competitor	基板伝送特性 評価 PCB High-Speed Line Measurement	✓			✓	✓				
セットメーカー OEM Supplier	高速デジタル伝送基板 評価支援 High-speed PCB Evaluate Support	✓	✓		✓	✓		✓		
	実機実装基板 製造開発 PCB Assembly Manufacturing	✓	✓	✓				✓	✓	✓

設計/解析 PCB Design/Simulation			比誘電率/誘電正接・界面導電率 Dk/Df & Interface Conductivity		伝送線路特性測定 S-parameter Measure	
伝送線路Sパラメータ解析 High Speed Line S-Parameter	熱流体解析 Electronics Cooling	熱応力解析 Thermal Stress	ベクトルネットワークアナライザ Vector Network Analyzer	平衡型円板共振器 BCDR Fixture	RFプローブ RF Probe	セミアートプローバー Semi-Auto Probe Station
 Circuit Simulation	 Cu-Inlay PCB	 12Layer AnyLayer PCB				

機能集積配線板 製造 Integrated Printed Subsystem Boards Manufacturing				加工条件 Process Condition		基板分析 PCB Analysis	
高周波材料基板 High-Speed Material PCB	FC-BGA基板 FC-BGA Substrate	めっき接続部品内蔵基板 Laser-Attachment Embedding PCB	はんだ接続部品内蔵基板 Solder-Attachment Embedding PCB	ビア形成 Via Formation	X線分析 X-ray	断面解析 X-section Analysis	EDX元素分析 EDX Analysis
 LCP	 FC-BGA Substrate	 8Layer HDI PCB	 8Layer HDI PCB	 LVH	 Memory Package	 Embedding PCB	FT-IR分析 FT-IR Analysis
 PTFE	 MOSFET Bare Chip	 4Layer HDI PCB	 0603C	 PTH			

信頼性試験 Reliability Test		特性評価 Performance Evaluation			
冷熱衝撃試験 Temperature Cycling Test	アイ・ダイアグラム Eye Diagram	電源インピーダンス GND-Impedance	FET表面温度(内蔵基板) FET Temperature (FC Embedding)	FET表面温度(銅インレイ基板) FET Temperature (Cu-Inlay)	
 Resistance Change Rate	 Eye Diagram	 GND-Impedance	 FET Temperature	 FET Temperature	
イオンマイグレーション試験 Temperature Humidity Bias Test	S21 Insertion Loss	Z11 Impedance	FET Embedding Substrate	FET Ass'y Area Assembly Structure	
 Insulation Resistance	 S21 Insertion Loss	 Z11 Impedance	 FET Embedding Substrate	 FET Ass'y Area Assembly Structure	
			Power Device Structure	FET Surface Temperature	
			 Power Device Structure	 FET Surface Temperature	